Discription

The HESDNC5VU1EL-A protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



SOD-323

Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Stand-off Voltage: 5 V
- ★ Peak Power up to 200 Watts @ 8 x 20 _s Pulse
- ★ Low Leakage
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 (> 16 kV) per Human Body Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ IEC61000-4-4 Level 4 EFT Protection
- ★ We declare that the material of product compliance with RoHS requirements.



Circuit Diagram

Ordering Information

Product ID	Pack	Qty(PCS)				
HESDNC5VU1EL-A	SOD-323	3000				

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20μs)	135	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±15 ±8	KV
	IEC61000-4-4 (EFT)	40	Α
	ESD Voltage Per Human Body Model	16	KV

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

Device	V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	I_	V _C (V) @ I _{PP} =5 A*	V _C (V) @ Max I _{PP} *	I _{PP} (A)*	P _{PK} (W)*	C (pF)
	Max	Max	Min	mA	Тур	Max	Max	Max	Тур
HESDNC5VU1EL-A	5.0	1.0	6.2	1.0	11.6	15	9	135	60

^{*}Surge current waveform per Figure 1.

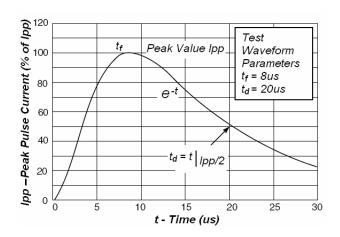


Fig1. Pulse Waveform

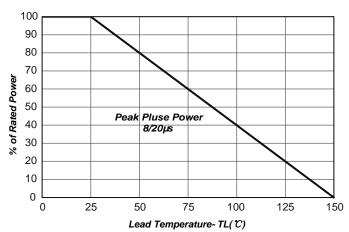
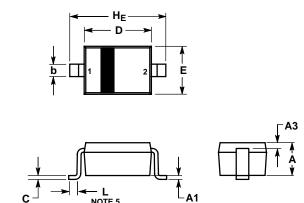


Fig2. Power Derating

^{1.} V_{BR} is measured with a pluse test current I_T at an ambient temperature of 25 $^\circ\!\!\!\!$ C .



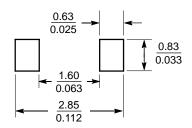
SOD-323



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MIL	LIMETE	ERS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.15 REF			0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.60	1.70	1.80	0.062	0.066	0.070	
Е	1.15 1.25		1.35	0.045	0.049	0.053	
L	0.08			0.003			
HF	2.30	2.50	2.70	0.090	0.098	0.105	

SOLDERING FOOTPRINT*





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